

ABSTRACT

A polyimide resin having phenolic hydroxyl radicals in
5 its skeleton is prepared using a diamine bearing an aromatic
ring having an amino radical attached thereto and another
aromatic ring having a phenolic hydroxyl radical. The
polyimide resin and a composition comprising the polyimide
resin, an epoxy resin and a curing agent are suited for use
10 as varnish, adhesive and adhesive film for which adhesion and
heat resistance are required.